

COPY

PATENT NUMBER

O.I.P.E.
 SCANNED PD2 G.A.

PATENT DATE	6/2
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Apparatus for and method of heat-treating a wafer

TITLE

PTO-2040
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ISSUING CLASSIFICATION												
ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

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